

**Gull Wing Type** 



**T-bend Type** 

# **FEATURES**

- End stackable for standard 0.1 integrated circuit pitch
- Molded 0.3 integrated circuit packing outline allowing automatic insertion
- Smaller size makes better heat convection during PC board reflow soldering
- Top tape sealed to withstand reflow soldering, board washing
- All plastics are UL 94V-0 grade fire retardant
- Twin contacts designed to ensure stable contact
- Gold plated contact to ensure low contact resistance and Tin plated terminals to prevent contamination during soldering
- RoHS Compliant

### **APPLICATIONS**

- Numerical setting for computer terminal equipment
- Price setting for vending machines
- Programming for game machines
- Programming for industrial equipment and measuring instruments

### **SPECIFICATIONS**

# ELECTRICAL

Contact rating

25 mA, 24 VDC switching 100 mA non-switching

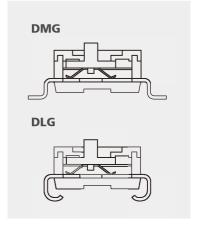
Contact resistance

 $50m\Omega$  Max. initial 100mΩ Max. after life test

 $1.000 \text{ M}\Omega$  Min. at 100 VDCInsulation resistance 500 VDC Min. for 60 seconds Dielectric strength

Capacitance between adjacent switches 5 pF Max

## CONSTRUCTION



# **MECHANICAL and ENVIRONMENTAL**

Temperature rating

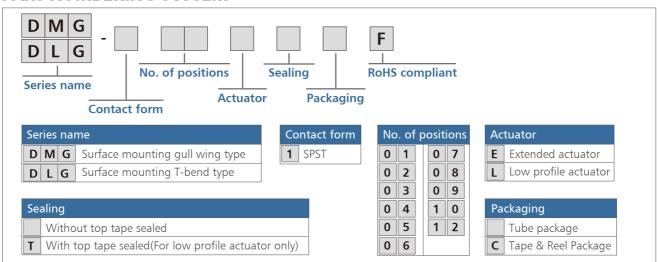
 $-40^{\circ}$ C to  $+85^{\circ}$ C operating -40°C to +85°C storage 800g Max. Operation force 2,000 operations Mechanical life 95%RH, 40°C for 96 Hrs. Humidity 10Hz - 55Hz - 10Hz for 6 Hrs. Vibration After flux 245±5 °C for 5±1 second Solderability

Resistance to soldering heat

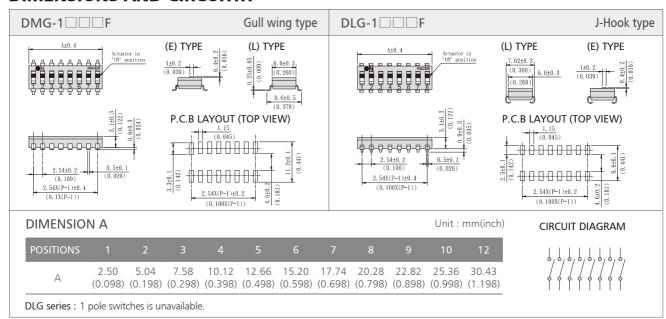
Solder reflow Peak temperature 260°C Max.

Reflow soldering process for SMT type Reference IEC 61760

# **PART NUMBERING SYSTEM**



## **DIMENSIONS AND CIRCUITRY**



### **OPTIONS**

### **PACKAGING**



